



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SERIES 896, 897 • UNIVERSAL SERIAL BUS 3.0 • SOCKETS

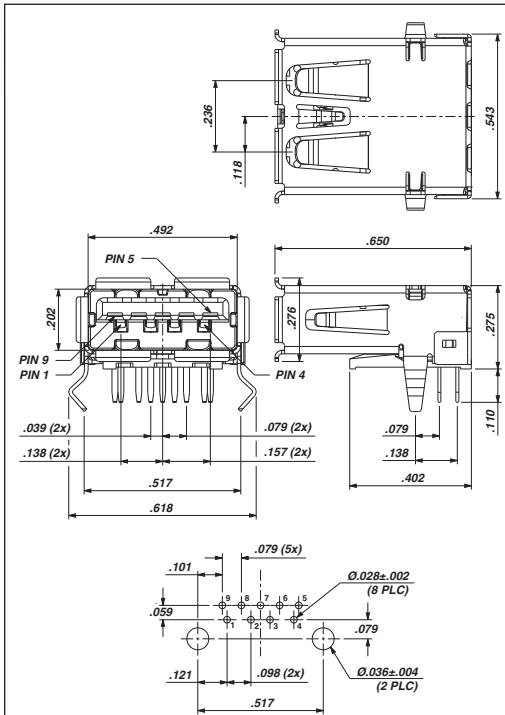


FIG. 1

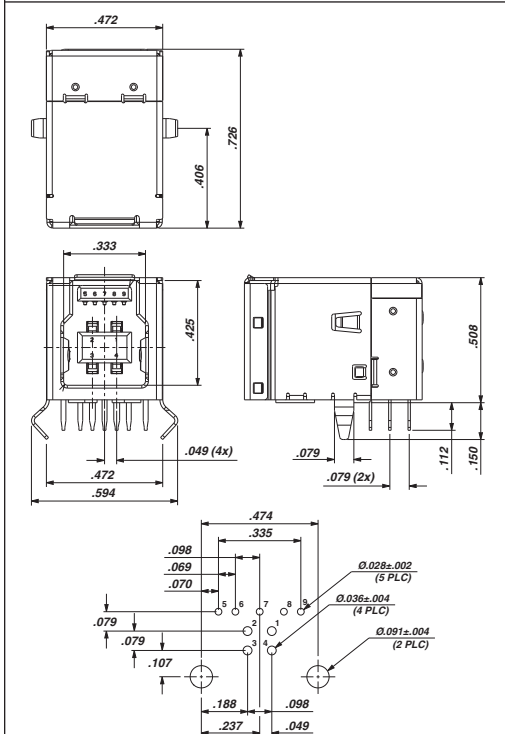
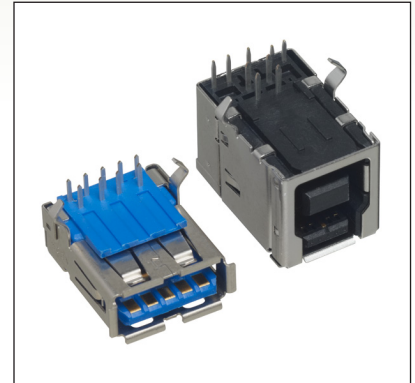


FIG. 2

- USB 3.0 receptacles for through-hole mount
- Plug retention tabs
- Kinked locating legs for secure PCB retention
- Fully shielded
- Fully backwards compatible with USB 2.0
- 10X faster than USB 2.0 and provides optimized power efficiency
- Packaged in trays:
896-46-009-90-300000 - 100 pieces per tray
897-46-009-90-300000 - 80 pieces per tray



ORDERING INFORMATION

FIG. 1	USB 3.0 Type A Receptacle, Single, Through-Hole
	896-46-009-90-300000
FIG. 2	USB 3.0 Type B Receptacle, Single, Through-Hole
	897-46-009-90-300000

Technical Specifications

Materials:

Terminals: Copper Alloy, Tin-Plated
 Contacts: Copper Alloy, Gold Flash over PdNi
 Casing and Shield: Stainless Steel
 Insulator material: High temperature thermoplastic rated UL94V-0



Ratings:

Voltage: 30VAC (rms)
 Current: 1.5A PWR/GND pins
 All housing materials rated for "lead-free" soldering up to 260° C

Electrical:

Contact resistance: 30mΩ max. for power and ground pins
 50mΩ max. for all others
 Insulation resistance: 100MΩ min.
 Dielectric withstanding voltage: 100VAC at sea level
 Capacitance: 2pF max.

Mechanical:

Random vibration: No discontinuity >1μs per EIA 364-28, cond. VII, letter D
 Physical shock: No discontinuity >1μs per EIA 364-27, condition H
 Durability: 5000 cycles min. per EIA 364-09
 Mating force: 35 Newtons max. per EIA 364-13
 Unmating force: Initial - 10 Newtons min. per EIA 364-13
 After test - 8 Newtons min. per EIA 364-13

Environmental:

Thermal shock per EIA 364-32, condition I
 Humidity per EIA 364-31
 Temperature life per EIA 364-17, method A
 Solderability per EIA 364-52, category 2